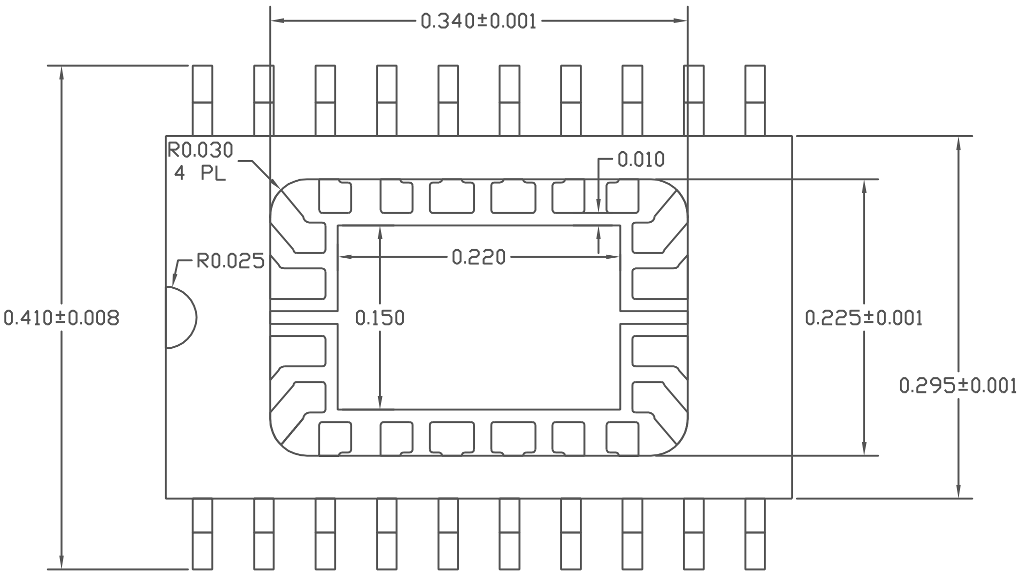
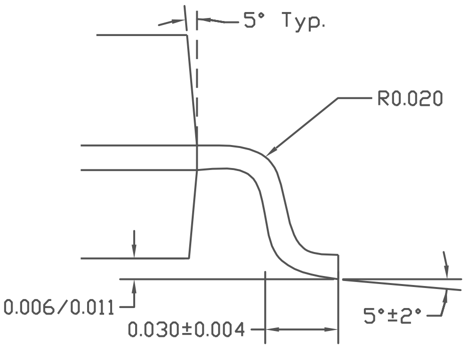
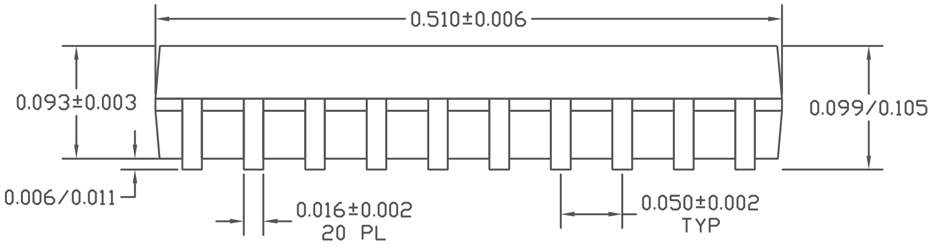
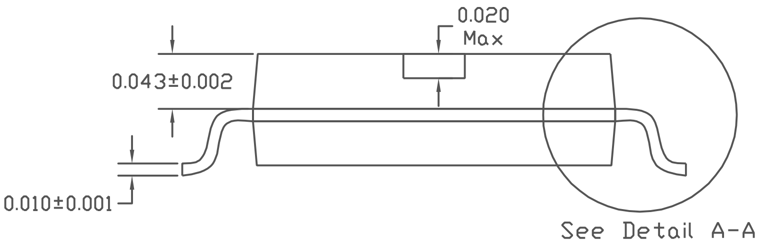
ECN	REV.	DESCRIPTION	DATE:	APP'D:
10005	-	INITIAL RELEASE	1/18/01	BF



DETAIL A-A







NOTES:

BODY : Plastic, Semiconductor Grade
LEAD FRAME : Copper, Olin 194
LEAD FINISH : 50 uIN Au, Over 50uIN Ni
DIE PAD : 0.220" x 0.150"

SPECTRUM
SEMICONDUCTOR MATERIALS, INC.

TITLE:
20 LEAD SOIC OPEN-PAK (Tooling Outline)

MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: S.O.
GEN. TOL.: ±.005	DATE: 12/10/00	APP'D: BF 1/18/01

SSM P/N:	DWG. NO.:	REV.
PSO203001	SOIC20-OP-01-T	-